

## AMENDMENTS

### In The Claims:

1-162. (canceled)

163. (previously added) An electronic package comprising:

a substrate comprising silicon;

a die joined with said substrate; and

an upper metallization structure over said die, wherein said upper metallization structure comprises an electroplated metal.

164. (previously added) The electronic package in claim 163, wherein a cavity is in said substrate and accommodates said die, said die having a bottom surface joined with the bottom of said cavity.

165. (previously added) The electronic package in claim 163, wherein said substrate has a top surface comprising a first region and a second region, said die joined with said first region, said second region not covered by said die, said first region being coplanar with said second region.

166. (currently amended) The electronic package in claim 163, wherein an opening is in said substrate and accommodates said die, said substrate having a top surface coplanar with a top surface of said die, ~~and a bottom surface coplanar with a bottom surface of said die.~~

167. (previously added) The electronic package in claim 163 further comprising a polymer layer under a metal layer of said upper metallization structure.

168. (previously added) The electronic package in claim 163 further comprising a polymer layer over a metal layer of said upper metallization structure.

169. (previously added) The electronic package in claim 163, wherein said die has a top surface at a horizontal level, said substrate being under said horizontal level, said upper metallization structure being over said horizontal level.

170. (previously added) The electronic package in claim 169, wherein said top surface comprises multiple pads.

171. (previously added) The electronic package in claim 169 further comprising a passive device over said horizontal level.

172. (previously added) The electronic package in claim 163, wherein said upper metallization structure further extending outside beyond an edge of said die.

173. (previously added) The electronic package in claim 163 further comprising an adhesive tape joining said die and said substrate.

174. (previously added) The electronic package in claim 163 further comprising an a conductive paste joining said die and said substrate.

175. (previously added) The electronic package in claim 163 further comprising a bump on a pad of said upper metallization structure, wherein said bump comprises solder.

176. (previously added) The electronic package in claim 163 further comprising a bump on a pad of said upper metallization structure, wherein said bump comprises gold.

177. (previously added) The electronic package in claim 163 further comprising a film layer over sad substrate and surrounding said die.

178. (previously added) The electronic package in claim 177, wherein said film layer comprises polymer.

179. (previously added) An electronic package comprising:

a substrate comprising silicon;  
a die joined with said substrate comprising multiple internal circuits; and  
an upper metallization structure over said die, wherein said upper metallization structure comprises a portion connecting said multiple internal circuits.

180. (previously added) The electronic package in claim 179, wherein a cavity is in said substrate and accommodates said die, said die having a bottom surface joined with the bottom of said cavity.

181. (previously added) The electronic package in claim 179, wherein said substrate has a top surface comprising a first region and a second region, said die joined with said first region, said second region not covered by said die, said first region being coplanar with said second region.

182. (previously added) The electronic package in claim 179, wherein an opening is in said substrate and accommodates said die, said substrate having a top surface coplanar with a top surface of said die, and a bottom surface coplanar with a bottom surface of said die.

183. (previously added) The electronic package in claim 179 further comprising a polymer layer under a metal layer of said upper metallization structure.

184. (previously added) The electronic package in claim 179 further comprising a polymer layer over a metal layer of said upper metallization structure.

185. (previously added) The electronic package in claim 179, wherein said portion is used to transmit a signal.

186. (previously added) The electronic package in claim 179, wherein said portion is used to provide a power voltage.

187. (previously added) The electronic package in claim 179, wherein said portion is used to provide a ground voltage.

188. (previously added) The electronic package in claim 179, wherein said die has a top surface at a horizontal level, said substrate being under said horizontal level, said upper metallization structure being over said horizontal level.

189. (previously added) The electronic package in claim 188, wherein said top surface comprises multiple pads.

190. (previously added) The electronic package in claim 188 further comprising a passive device over said horizontal level.

191. (previously added) The electronic package in claim 179, wherein said upper metallization structure further extending outside beyond an edge of said die.

192. (previously added) The electronic package in claim 179 further comprising an adhesive tape joining said die and said substrate.

193. (previously added) The electronic package in claim 179 further comprising an a conductive paste joining said die and said substrate.

194. (previously added) The electronic package in claim 179 further comprising a bump on a pad of said upper metallization structure, wherein said bump comprises solder.

195. (previously added) The electronic package in claim 179 further comprising a bump on a pad of said upper metallization structure, wherein said bump comprises gold.

196. (previously added) The electronic package in claim 179 further comprising a film layer over said substrate and surrounding said die.

197. (previously added) An electronic component comprising:

a die having a top surface at a horizontal level, wherein said die comprises multiple internal circuits; and

an upper metallization structure over said horizontal level, wherein said upper metallization structure comprises a portion connecting said multiple internal circuits and used to provide a ground voltage, wherein said upper metallization structure extends outside beyond an edge of said die.

198. (previously added) The electronic component in claim 197 further comprising a substrate joined with said die.

199. (previously added) The electronic component in claim 198, wherein said substrate comprises silicon.

200. (previously added) The electronic component in claim 198, wherein a cavity is in said substrate and accommodates said die, said die having a bottom surface joined with the bottom of said cavity.

201. (previously added) The electronic component in claim 198, wherein said substrate has a top surface comprising a first region and a second region, said die joined with said first region, said second region not covered by said die, said first region being coplanar with said second region.

202. (previously added) The electronic component in claim 197 further comprising a polymer layer under a metal layer of said upper metallization structure.

203. (previously added) The electronic component in claim 197 further comprising a polymer layer over a metal layer of said upper metallization structure.

204. (currently amended) The electronic component in claim 197 further comprising a film layer, wherein an opening is in said film layer and accommodate said die, said film layer having a top surface coplanar with said top surface of said die, ~~and a bottom surface coplanar with a bottom surface of said die.~~

205. (currently amended) The electronic component in claim ~~204~~ 197, wherein said film layer comprises polymer.

206. (currently amended) The electronic component in claim 197, wherein said portion ~~comprises is a ground bus, shape.~~

207. (previously added) The electronic component in claim 197, wherein said top surface of said die comprises multiple pads.

208. (previously added) The electronic component in claim 197 further comprising a passive device over said horizontal level.